

ABSTRACT

This invention is an improved adhesive composition prepared from at least one organic polymer resin, an inorganic filler, and a fugitive liquid, in which the liquid and organic polymer resin are each substantially insoluble in the other; and in which the improvement comprises that the at least one organic polymer resin be present in particulate form of particle size that is 25 μ or smaller. Adhesive compositions so prepared can be used on dies 400mil X 400mil or greater on metal substrates without significant delamination.

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